

Title (en)  
INTERCONNECTION SYSTEM

Title (de)  
VERBINDUNGSSYSTEM

Title (fr)  
SYSTEME D'INTERCONNEXION

Publication  
**EP 1543588 A4 20070411 (EN)**

Application  
**EP 03765915 A 20030723**

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Abstract (en)  
[origin: WO2004010749A2] An interconnection system includes spacers arranged adjacent each other in a row, the spacers having printed circuit boards disposed therebetween. Each printed circuit board has at least one pair of electrical conductors respectively disposed on opposite faces thereof. All of the printed circuit boards have one end exposed on a first plane and a second end exposed on a second plane. Electrically conductive contacts are disposed within cells in a pair of interposers so as to have one end making electrical contact with one of the printed circuit boards and another end extending through its respective cell in its respective interposer.

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IPC 8 full level  
**H01L 23/32** (2006.01); **H01R 13/646** (2011.01); **H01R 13/514** (2006.01)

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**H01R 13/6592** (2013.01 - EP); **H01R 24/50** (2013.01 - EP); **H01R 12/716** (2013.01 - EP); **H01R 12/724** (2013.01 - EP);  
**H01R 12/737** (2013.01 - EP); **H01R 13/514** (2013.01 - EP); **H01R 2103/00** (2013.01 - EP)

Citation (search report)  

- No further relevant documents disclosed
- See references of WO 2004010749A2

Cited by  
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AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)  
**WO 2004010749 A2 20040129; WO 2004010749 A3 20040701**; AU 2003263799 A1 20040209; AU 2003263799 A8 20040209;  
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